## **Amendments to the Claims**

The following listing of claims shall supersede all previously submitted versions.

## **Claims Listing**

1. (Currently Amended) A method for determining a target lifetime for a physical vapor deposition tool, comprising the steps of:

selecting criteria for a minimum accumulating rate of <u>a number of</u>  $\triangle$  wafers fabricated <u>per unit of deposit time</u> by <u>a change in</u>  $\triangle$  target life for a target in the tool;

recording actual values of <u>the number of</u>  $\triangle$  wafers fabricated <u>per unit of deposit time</u> by <u>the change in</u>  $\triangle$  target life for a target in the tool; for a time period;

comparing a calculated, reported accumulating rate with a calculated, minimum accumulating rate, and

checking the condition of the target in the tool,

deciding whether to replace the target, when the reported accumulating rate is less than the minimum accumulating rate.

(Currently Amended) The method of claim 1, and further comprising the steps of:
recording the criteria in a table for multiple targets in respective multiple ones of the tool;
and

selecting the criteria by retrieving the criteria from the table.

- 3. (Currently Amended) The method of claim 1, and further comprising the step of: generating an alarm when the reported accumulating rate is less than the minimum accumulating rate.
- 4. (Currently Amended) The method of claim 1, wherein, the step of selecting criteria for a minimum accumulating rate, further comprises the step of selecting the criteria of thinnest wafers fabricated by the tool for a minimum accumulating rate of the number of  $\Delta$  thinnest wafers fabricated per unit of deposit time by the change in  $\Delta$  target life for a target in the tool.
- 5. (Currently Amended) The method of claim 4, and further comprising the step of: recording the criteria in a table for multiple targets in respective multiple ones of the tool.

- 6. (Currently Amended) The method of claim 4, and further comprising the step of: generating an alarm when the reported accumulating rate is less than the minimum accumulating rate.
- 7. (Currently Amended) The method of claim 1, wherein, the step of comparing a calculated reported accumulating rate with a calculated, minimum accumulating rate, further comprises the step of comparing a graph of the reported accumulating rate with a slope of the minimum accumulating rate for one KWH of tool power.
- 8. (Currently Amended) The method of claim 7, and further comprising the step of: generating an alarm when the graph has a slope that is less than the slope of the minimum accumulating rate for one KWH of tool power.
- 9. (Currently Amended) The method of claim 7, and further comprising the step of: recording the criteria in a table for multiple targets in respective multiple ones of the tool.
- 10. (Currently Amended) The method of claim 7, and further comprising the step of: generating an alarm when the reported accumulating rate is less than the minimum accumulating rate.
- 11. (Currently Amended) The method of claim 7, wherein, the step of selecting criteria for a minimum accumulating rate, further comprises the step of selecting the criteria of thinnest wafers fabricated by the tool for a minimum accumulating rate of the number of  $\triangle$  thinnest wafers fabricated per unit of deposit time by the change in  $\triangle$  target life for a target in the tool.
- 12. (Currently Amended) A system for determining a lifetime of a target for a physical vapor deposition tool, comprising:
- a mapping table of criteria for a minimum accumulating rate of <u>a number of</u>  $\Delta$  wafers fabricated <u>per unit of deposit time</u> by <u>the change in</u>  $\Delta$  target life for a target in the tool;
- a database recording the number of  $\Delta$  wafers fabricated per unit of deposit time by the change in  $\Delta$  target life for a target in the tool; and
- a computer retrieving the criteria from the mapping table and entering the criteria in the database; and

wherein the tool is configured to (a) compare a calculated reported accumulating rate with the minimum accumulating rate; (b) reporting the number of  $\Delta$  wafers fabricated per unit of deposit time by the change in  $\Delta$  target life for a target in the tool for comparison with the criteria; and (c) deciding whether to replace the target when the reported accumulating rate is less than the minimum accumulating rate.